Surface Mount Fuses

Thin Film > 1206 Size > Very Fast-Acting > 466 Series

466 Series Fuse

pertise Applied | Answers Delivered











Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE		
71	E10480	125mA - 5A		
(P)	LR29862	125mA - 5A		

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C	
100%	4 hours, Minimum	
200%	5 sec., Maximum	
300%	0.2 sec., Maximum	

Additional Information







Samples

Description

The 466 Series Fast-Acting Surface Mount Fuse (SMF) is a small (1206 size) thin-film device designed for secondary protection of circuits used in space constrained applications such as hand-held portable electronic devices.

This series is 100% lead-free and meets the requirements of the RoHS directive. New Halogen-Free 466 Series fuses are available to order using the "HF" suffix. See Part Numbering section for additional information.

Features

- Product is compatible with lead-free solders and higher temperature profiles
- Product is marked on top surface with code to allow amperage rating identification without testing
- Low profile for height sensitive applications
- Flat top surface for pickand-place operations

- Element-covering material is resistant to industry standard cleaning operations
- Mounting pad and electrical performance are identical to Littelfuse 429 and 433 Series products
- Alloy-based element construction provides superior inrush withstand characteristics (I2t) over ceramic or glass-based 1206 chip fuse products

Applications

Secondary protection for space constrained applications:

- Cell phones
- Battery packs
- · Digital cameras
- DVD players · Hard disk drives

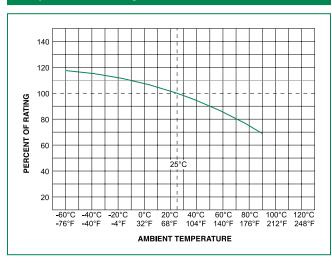
Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I²t (A²sec)	Nom Voltage Drop (mV)	Nom Power Dissipation (W)	Agency A	Approvals (1)
0.125	.125	125	50A @125 V AC/ DC	4.000	0.00040	552.66	0.0691	X	Х
0.200	.200	125		1.160	0.00055	254.28	0.0509	Х	Х
0.250	.250	125		0.710	0.0010	207.01	0.0518	Х	Х
0.375	.375	125		0.350	0.0028	169.18	0.0634	X	X
0.500	.500	63	50A @63 V AC/DC	0.248	0.0060	158.47	0.0792	Х	Х
0.750	.750	63		0.111	0.0276	98.65	0.0740	Х	Х
1.00	001.	63		0.076	0.0423	89.94	0.0899	Х	Х
1.25	1.25	63		0.059	0.0640	85.71	0.1071	X	X
1.50	01.5	63		0.048	0.1103	82.97	0.1244	Х	Х
1.75	1.75	63		0.039	0.1323	80.73	0.1413	Х	Х
2.00	002.	63		0.031	0.2326	78.73	0.1575	X	X
2.50	02.5	32	50A @32 V AC/DC	0.024	0.3516	76.99	0.1925	Х	Х
3.00	003.	32		0.020	0.5760	75.99	0.2280	Х	Х
4.00	004.	32		0.014	1.024	74.50	0.2980	Х	Х
5.00	005.	32		0.011	1.600	73.75	0.3688	Х	Х

- 1 Measured at 10% of rated current 25°C
- 2. Measured at rated voltage.



Temperature Rerating Curve



Note:

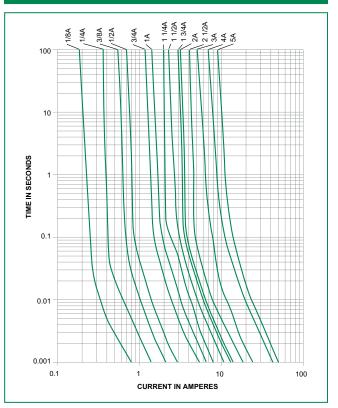
 Rerating depicted in this curve is in addition to the standard rerating of 25% for continuous operation.

Example:

For continuous operation at 70 degrees celsius, the fuse should be rerated as follows: $I = (0.75)(0.80)I_{BAT} = (0.60)I_{BAT}$

The temperature derating curve represents the nominal conditions. For questions about temperature derating curve, please consult Littelfuse technical support for assistance.

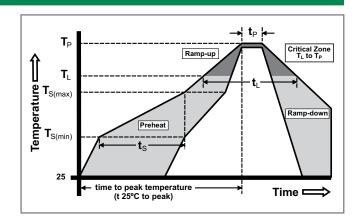
Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 seconds	
Average R (T _L) to pea	Ramp-up Rate (Liquidus Temp ak)	5°C/second max.	
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
	-Temperature (t _L)	60 – 150 seconds	
PeakTemperature (T _P)		260+0/-5 °C	
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-down Rate		5°C/second max.	
Time 25°C	to peakTemperature (T _P)	8 minutes max.	
Do not ex	ceed	260°C	





Surface Mount Fuses

Product Characteristics

Materials	Body: Advanced High Temperature Substrate Terminations: 100% Tin over Nickel over Copper Element Cover Coat: Conformal Coating		
Operating Temperature	– 55°C to 90°C. Consult temperature rerating curve chart.		
Thermal Shock	Withstands 5 cycles of –55°C to 125°C		
Humidity	MIL-STD-202F, Method 103B, Condition D		
Vibration	Per MIL-STD-202F, Method 201A		
Insulation Resistance (After Opening)	Greater than 10,000 ohms		
Resistance to Soldering Heat	MIL-STD-202G, Method 210F, Condition D		

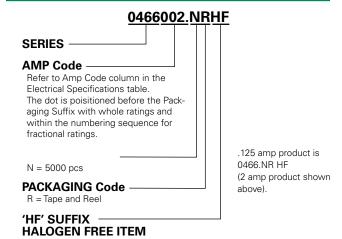
Part Marking System

Amp Code	Marking Code
.125	В
.200	С
.250	D
.375	E
.500	F
.750	G
001.	Н
1.25	J
01.5	K
1.75	L
002.	N
02.5	0
003.	Р
004.	S
005.	Т

Dimensions MARKING CODE VARIES WITH AMPERAGE RATING (SEE CHART) 0.660 ± 0.127 (0.026" ± 0.005") 0.584 ± 0.076 (0.023" ± 0.003") 0.559 ± 0.127 3.175 ± 0.127 (0.125" ± 0.005") $(0.022" \pm 0.005")$ 1.524 ± 0.127 $(0.060" \pm 0.005")$ 3.175 ± 0.127 (0.125" ± 0.005") 1.65 (.065")1.52 4.83 (.190") 3.81 (.060") (.150") (.045") 2.03 2.03

Part Numbering System

WAVE SOLDER



REFLOW SOLDER

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA-481 Rev. D (IEC 60286, part 3)	5000	NR